DB3J315E

Silicon epitaxial planar type

For high speed switching circuits DB3X315E in SMini3 type package

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

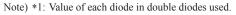
■ Marking Symbol: 5D

■ Packaging

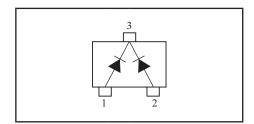
DB3J315E0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit		
Reverse voltage		V _R	30	V	
Maximum peak reverse voltage		V _{RM}	30	V	
Forward current	Single	T	30	mA	
	Double *1	$I_{\rm F}$	20		
Peak forward current	Single	,	150	mA	
	Double *1	I _{FM}	110		
Junction temperature		T _j	125	°C	
Operating ambient temperature		Topr	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C		



Unit: mm 2.0 0, 3 0.13 0.9 (0. 65)(0. 65) 1.3 1: Anode-1 3: Cathode-1 2: Anode-2 Cathode-2 SMini3-F2-B Panasonic **JEITA** SC-85 Code

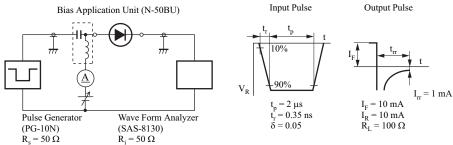


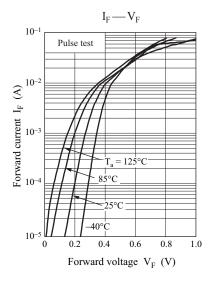
■ Electrical Characteristics $T_a = 25$ °C±3°C

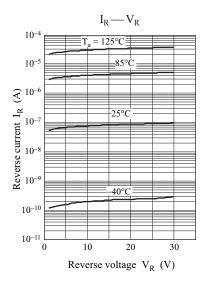
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V_{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I_R	$V_R = 30 \text{ V}$			300	nA
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		1.4		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$		1.0		ns

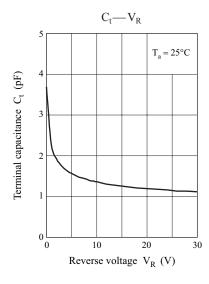
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz
 - *1: trr measurement circuit





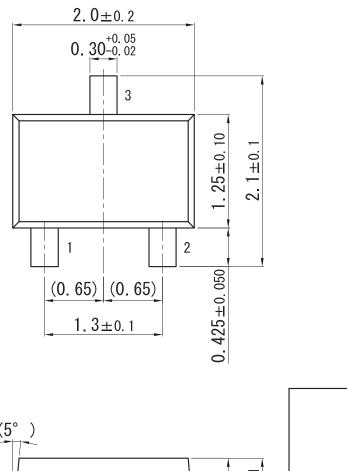


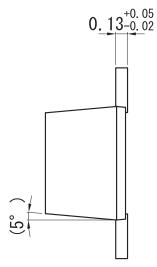


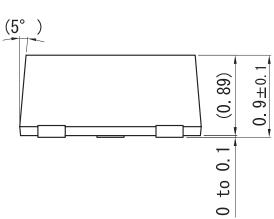
Ver. DED 2

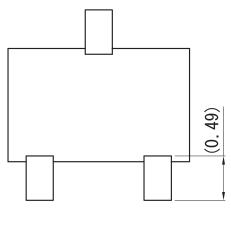
SMini3-F2-B

Unit: mm

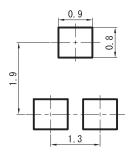








■ Land Pattern (Reference) (Unit: mm)



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